



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



Solder Spheres for BGAs

Product Highlights

Chip Quik® BGA solder spheres are manufactured from virgin materials to meet or exceed the requirements of building or repairing BGA packages. Chip Quik® BGA solder spheres also exceed both the IPC and MIL standards for purity levels and size tolerances. Nominal sizes are available from 12 to 30 mil.

Product Specifications

Part Number	Alloy	Melting Point	Diameter	Quantity (by weight)
SMD2165	Sn63/Pb37	183°C (361°F)	0.012" (0.305mm)	250,000
SMD2165-25000	Sn63/Pb37	183°C (361°F)	0.012" (0.305mm)	25,000
SMD2190	Sn63/Pb37	183°C (361°F)	0.020" (0.508mm)	250,000
SMD2190-25000	Sn63/Pb37	183°C (361°F)	0.020" (0.508mm)	25,000
SMD2200	Sn63/Pb37	183°C (361°F)	0.024" (0.610mm)	250,000
SMD2200-25000	Sn63/Pb37	183°C (361°F)	0.024" (0.610mm)	25,000
SMD2205	Sn63/Pb37	183°C (361°F)	0.025" (0.635mm)	250,000
SMD2205-25000	Sn63/Pb37	183°C (361°F)	0.025" (0.635mm)	25,000
SMD2215	Sn63/Pb37	183°C (361°F)	0.030" (0.762mm)	250,000
SMD2215-25000	Sn63/Pb37	183°C (361°F)	0.030" (0.762mm)	25,000
SMD2040	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.020" (0.508mm)	250,000
SMD2040-25000	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.020" (0.508mm)	25,000
SMD2050	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.024" (0.610mm)	250,000
SMD2050-25000	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.024" (0.610mm)	25,000
SMD2055	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.025" (0.635mm)	250,000
SMD2055-25000	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.025" (0.635mm)	25,000
SMD2060	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.030" (0.762mm)	250,000
SMD2060-25000	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.030" (0.762mm)	25,000

Shelf Life: >24 months

Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

Conforms to the following Industry Standards:

J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):
RoHS 2 Directive 2011/65/EU:

Yes
Yes (Sn96.5/Ag3.0/Cu0.5) /
No (Sn63/Pb37)